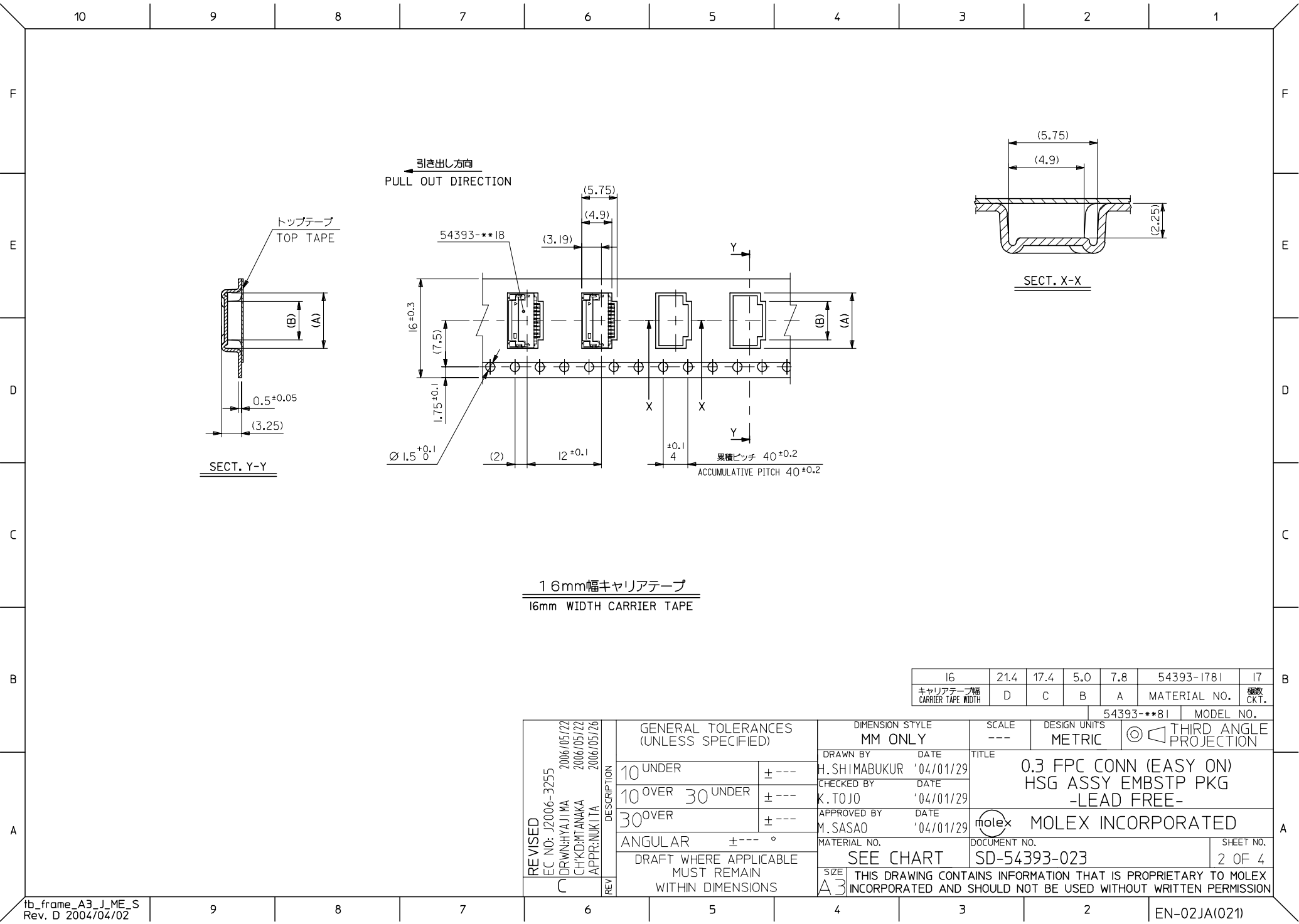
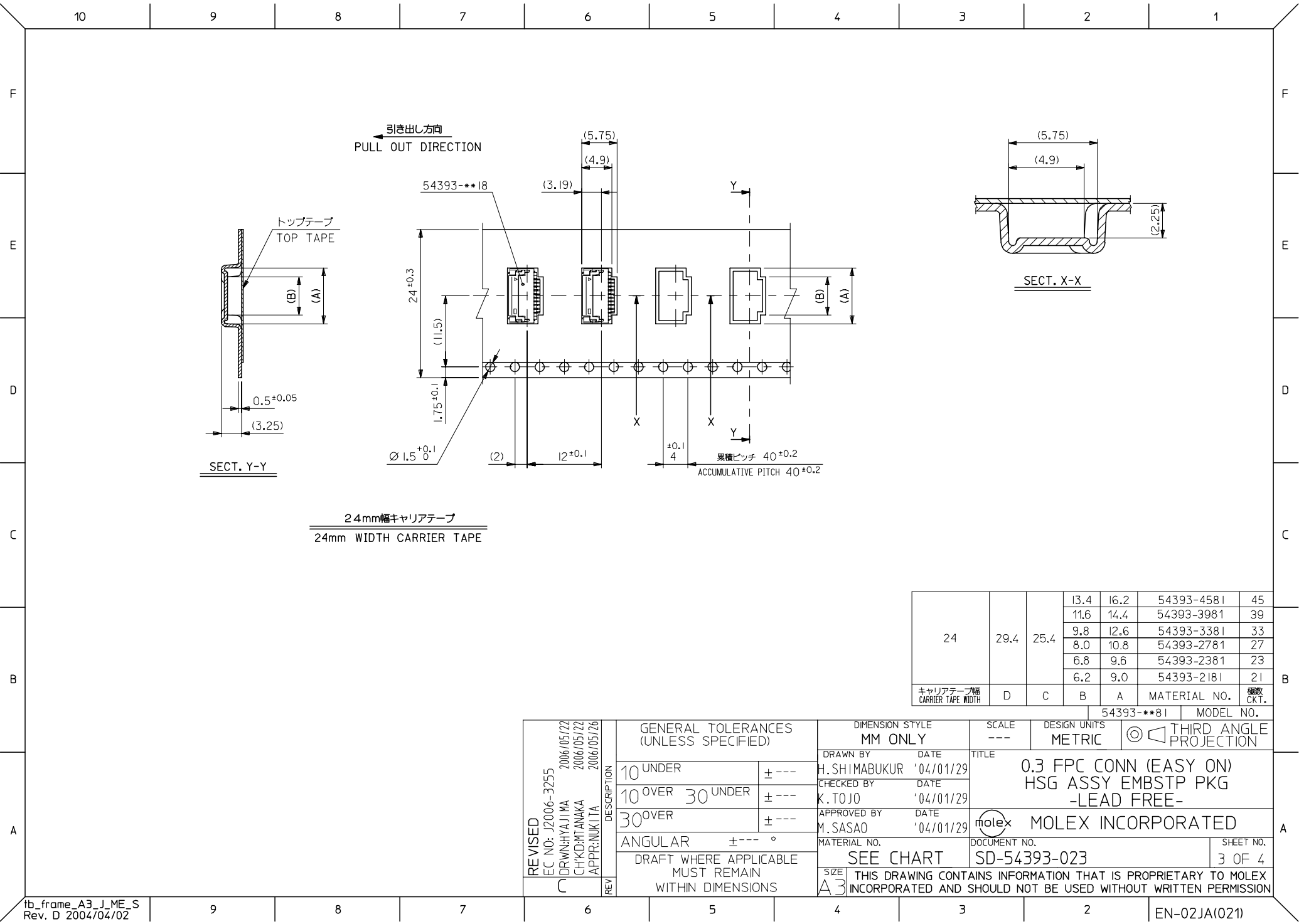




16mm 幅キャリアテープ
16mm WIDTH CARRIER TAPE

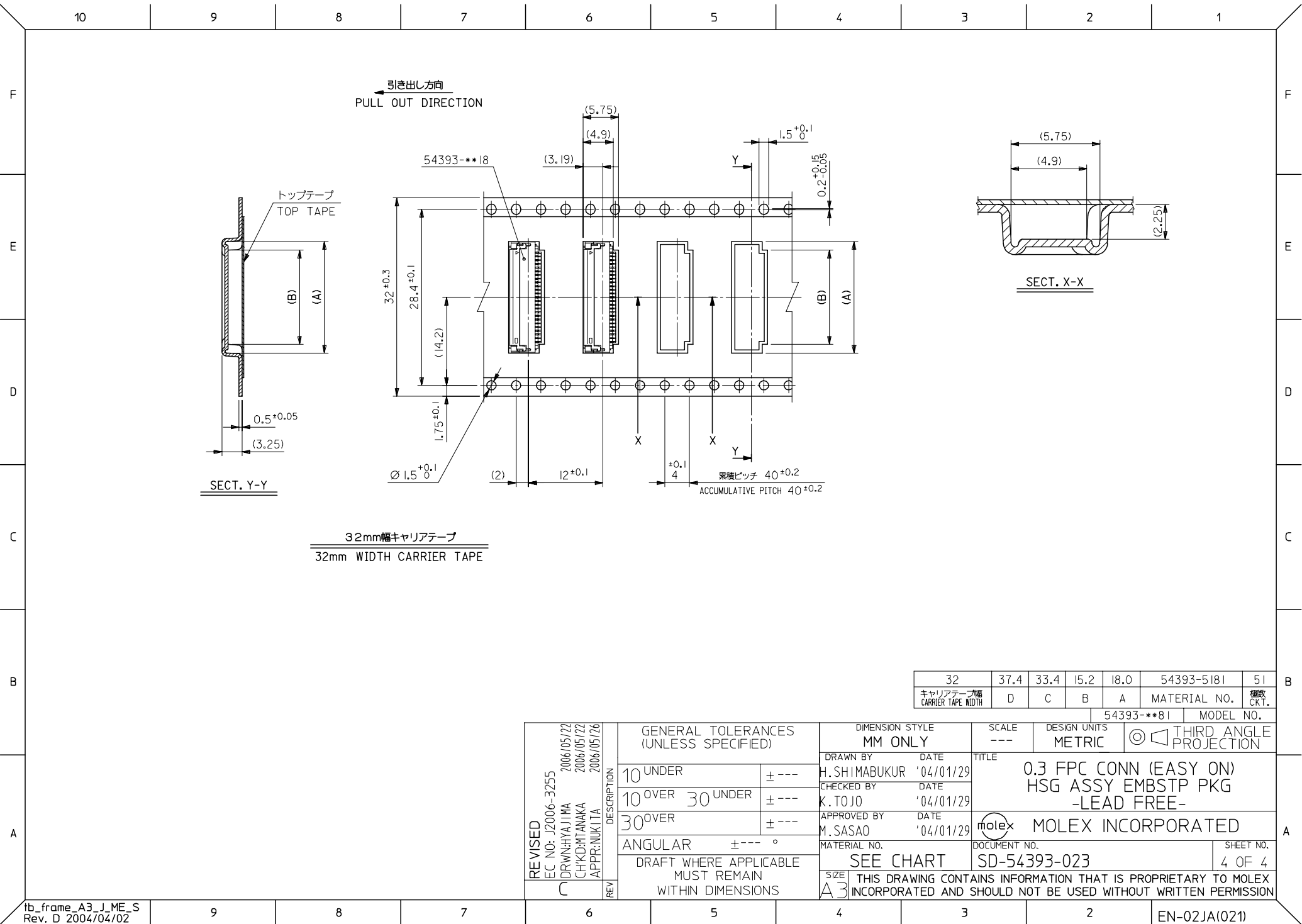
16	21.4	17.4	5.0	7.8	54393-1781	17
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	図面 CKT.

REVISED EC NO: J2006-3255 DRW:HYAJIWA CHKD:MTANAKA APPR:NUKITA C	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY H. SHIMABUKUR	DATE '04/01/29	TITLE 0.3 FPC CONN (EASY ON) HSG ASSY EMBSTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '04/01/29				
		30 OVER	± ---	APPROVED BY M. SASAO	DATE '04/01/29	 MOLEX INCORPORATED			
		ANGULAR	± --- °	MATERIAL NO. SEE CHART					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
				SIZE A3					

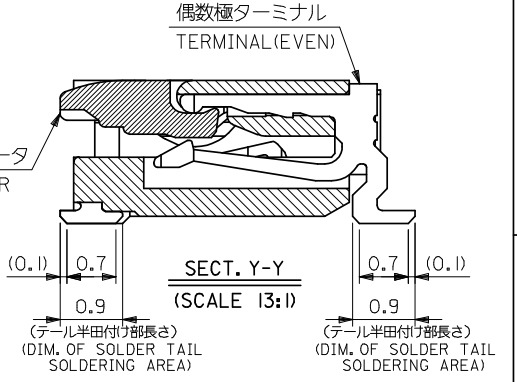
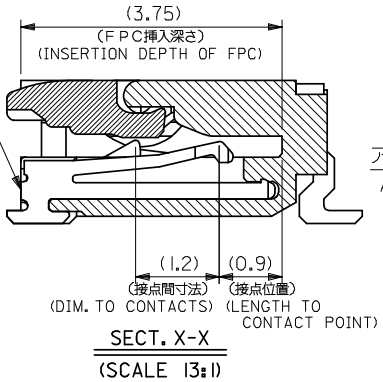
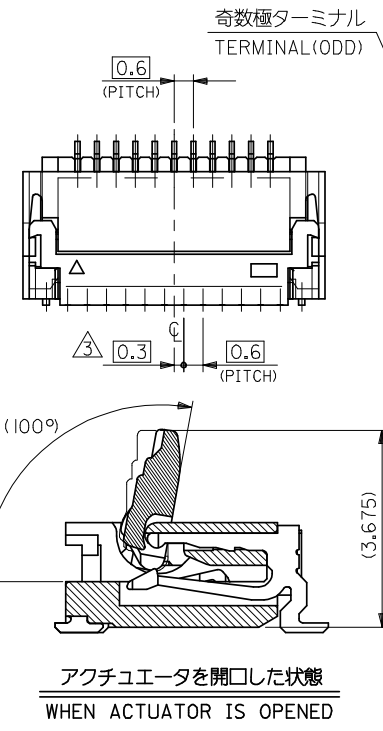
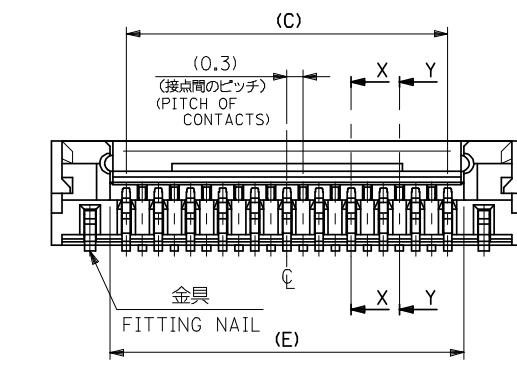
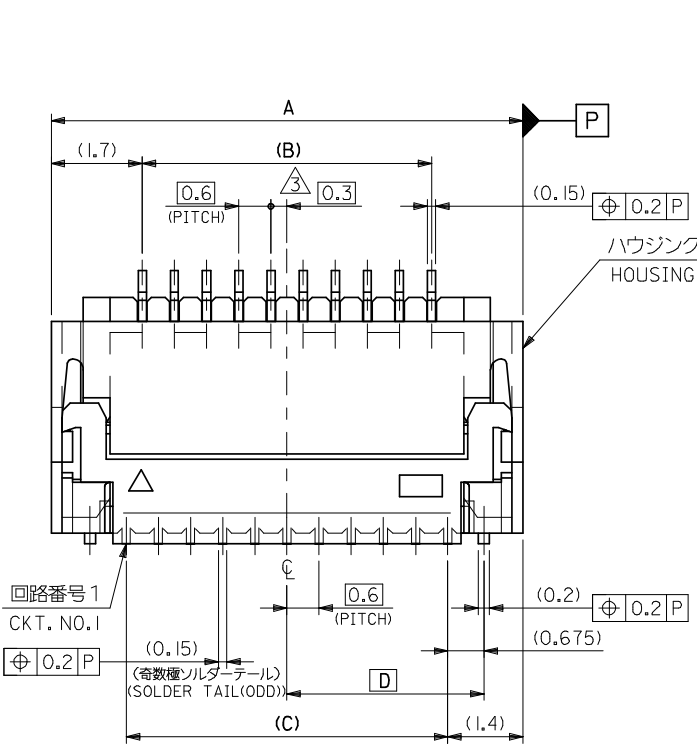


24	29.4	25.4	13.4	16.2	54393-4581	45
			11.6	14.4	54393-3981	39
			9.8	12.6	54393-3381	33
			8.0	10.8	54393-2781	27
			6.8	9.6	54393-2381	23
			6.2	9.0	54393-2181	21
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	数量 CKT.

REVISED EC NO: J2006-3255 DRW:HYAJIMA CHKD:MTANAKA APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY H.SHIMABUKUR	DATE '04/01/29	TITLE 0.3 FPC CONN (EASY ON) HSG ASSY EMBSTP PKG -LEAD FREE-				
		10 OVER 30 UNDER	± ---	CHECKED BY K.TOJO	DATE '04/01/29					
		30 OVER	± ---	APPROVED BY M.SASAO	DATE '04/01/29	molex MOLEX INCORPORATED				
		ANGULAR ±--- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



F
E
D
C
B
A



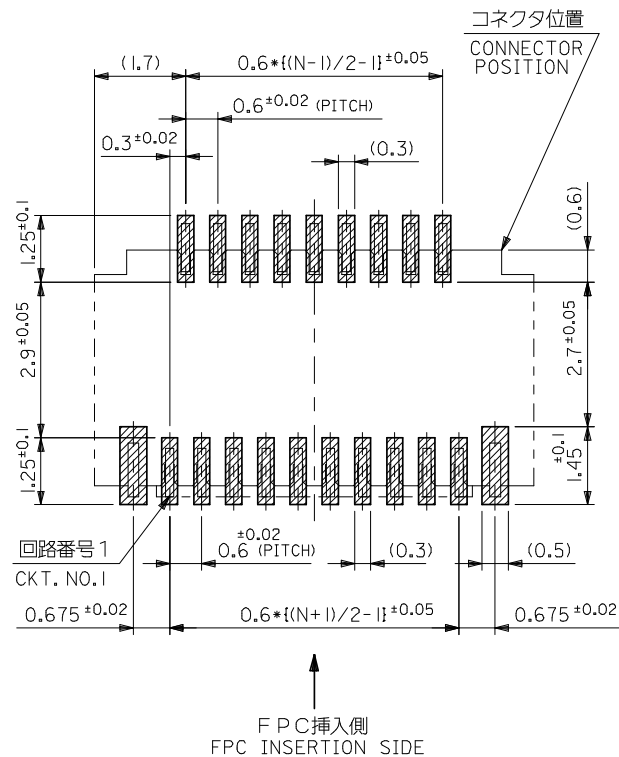
注記 NOTES

1. 使用材料 MATERIAL
ハウジング : LCP , UL94V-0
HOUSING
アクチュエータ : PPS , UL94V-0
ACTUATOR
ターミナル : リン青銅 (t=0.15) , ニッケル下地金メッキ
TERMINAL PHOS-BRO. , GOLD OVER NICKEL PLATING.
金具 : リン青銅 (t=0.2) , ニッケル下地金メッキ
FITTING NAIL PHOS-BRO. , TIN OVER NICKEL PLATING.
2. ソルダーテール半田付け面のスレ量、及び金具半田付け面のスレ量は、基準面 R に対し、
上方向 OMAX. , 下方向 0.18 MAX. とする。
又、相互のバラツキ量は 0.1 MAX. とする。
3. MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM R
UPPER DIRECTION : 0 MAX. , LOWER DIRECTION : 0.18 MAX.
OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAX.
4. (N-1) / 2 が偶数の場合、偶数極側に適用。
(N-1) / 2 が奇数の場合、奇数極側に適用。
IF (N-1) / 2 = EVEN, APPLY FOR
EVEN CIRCUIT SIDE,
IF (N-1) / 2 = ODD, APPLY FOR
ODD CIRCUIT SIDE,
4. 一般公差 : ±0.3
GENERAL TOLERANCES : ±0.3
5. 本製品は 54393-***77
の鉛フリー品です
THIS PRODUCT IS LEAD FREE
OF 54393-***77

15.6	8.175	15	14.4	17.8	54393-5181	54393-5118	51
13.8	7.275	13.2	12.6	16	54393-4581	54393-4518	45
12	6.375	11.4	10.8	14.2	54393-3981	54393-3918	39
10.2	5.475	9.6	9	12.4	54393-3381	54393-3318	33
8.4	4.575	7.8	7.2	10.6	54393-2781	54393-2718	27
7.2	3.975	6.6	6.0	9.4	54393-2381	54393-2318	23
6.6	3.675	6	5.4	8.8	54393-2181	54393-2118	21
5.4	3.075	4.8	4.2	7.6	54393-1781	54393-1718	17
E	D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	CKT.

54393-***18 MODEL NO.

REVISED EC NO: J2008-4034 D	DESCRIPTION 2008/05/28 2008/05/28 2008/05/28 2008/05/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY H. SHIMABUKUR	DATE '04/01/29	TITLE 0.3 FPC CONN (EASY ON) HSG ASSY -LEAD FREE-				
		10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '04/01/29					
		30 OVER	± ---	APPROVED BY M. SASAO	DATE '04/01/29	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO. SEE TABLE						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
		REV	D	SIZE A3						

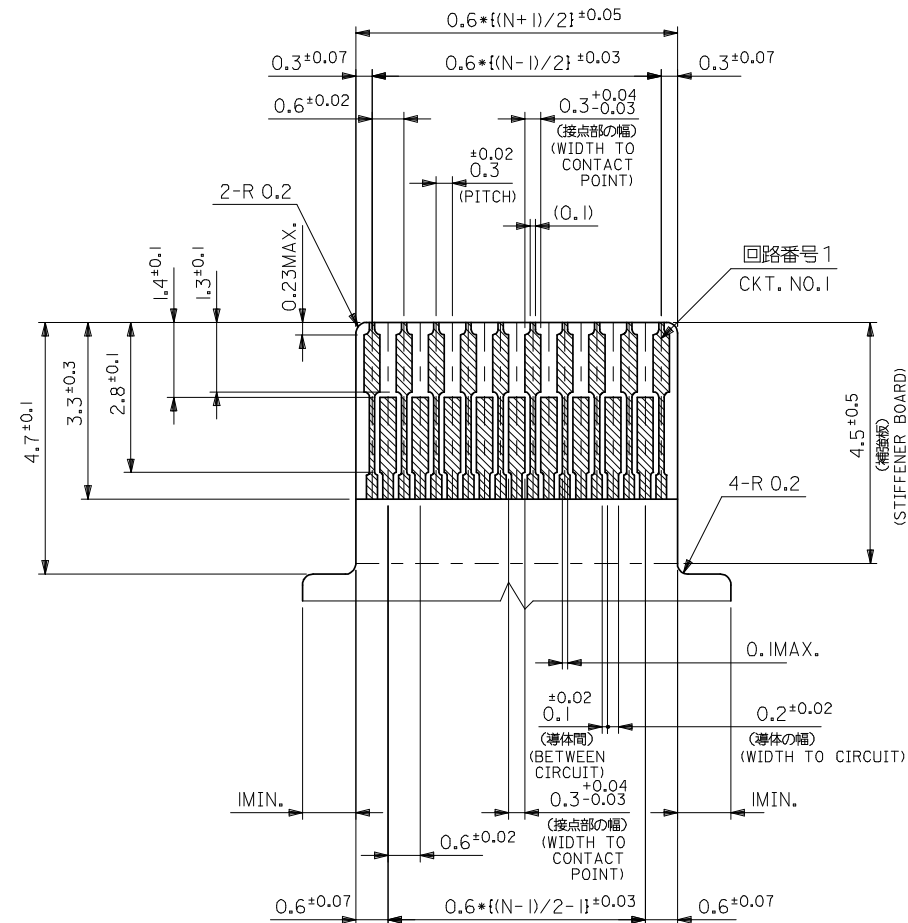


参考基板レイアウト
RECOMMENDED P.C.BOARD
PATTERN DIM. (REF.)
(マウント面)
(MOUNTING SIDE)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIM.

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS : 0.2 ± 0.03)

REVISED	EC NO: J2008-4034		2008/05/28		DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION						
	D	DRWN:MNABEI		2008/05/28		10 UNDER ± ---		DRAWN BY H. SHIMABUKUR DATE '04/01/29		TITLE 0.3 FPC CONN (EASY ON) HSG ASSY -LEAD FREE-								
		CHKD:THARUYAMA		2008/05/28		10 OVER 30 UNDER ± ---		CHECKED BY K. TOJO DATE '04/01/29										
		APPR:NUKITA		2008/05/28		30 OVER ± ---		APPROVED BY M. SASAO DATE '04/01/29		molex MOLEX INCORPORATED								
		REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ± --- °		MATERIAL NO. SEE SHEET 1						DOCUMENT NO. SD-54393-024		SHEET NO. 2 OF 2		